

Solid State Relay OCMOS FET

# PS7141-1C,PS7141L-1C

## 8-PIN DIP, 400 V BREAK DOWN VOLTAGE TRANSFER TYPE 2-ch Optical Coupled MOS FET

-NEPOC Series-

#### **DESCRIPTION**

The PS7141-1C and PS7141L-1C are transfer type solid state relays containing normally open (N.O.) contact and normally close (N.C.) contact on output side.

They are suitable for analog signal control because of their low offset and high linearity.

The PS7141L-1C has a surface mount type lead.

#### **FEATURES**

- 2 channel type (1 a + 1 b output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- · Small package (8-pin DIP)
- Low offset voltage
- Ordering number of taping product: PS7141L-1C-E3, E4: 1 000 pcs/reel

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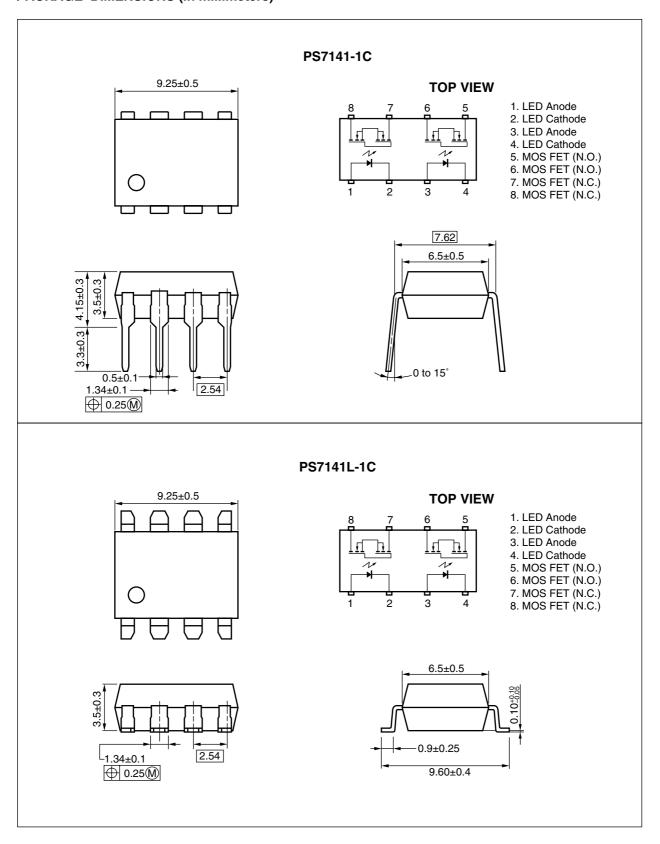
- · Pb-Free product
- · Safety standards
  - UL approved: File No. E72422BSI approved: No. 8245/8246
  - CSA approved: No. CA 101391

#### **APPLICATIONS**

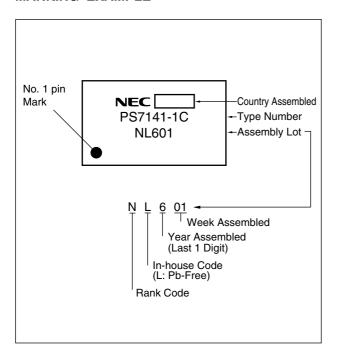
- · Exchange equipment
- · Measurement equipment
- · FA/OA equipment

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## **PACKAGE DIMENSIONS (in millimeters)**



## <R> MARKING EXAMPLE



## <R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number
PS7141-1C	PS7141-1C-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7141-1C
PS7141L-1C	PS7141L-1C-A			(UL, BSI, CSA	
PS7141L-1C-E3	PS7141L-1C-E3-A		Embossed Tape 1 000 pcs/reel	approved)	
PS7141L-1C-E4	PS7141L-1C-E4-A				

<sup>\*1</sup> For the application of the Safety Standard, following part number should be used.

## ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit	
Diode	Forward Current (DC)	lF	50	mA/ch	
	Reverse Voltage	VR	5.0	V	
	Power Dissipation	PD	50	mW/ch	
	Peak Forward Current <sup>™</sup>	IFP	1	A/ch	
MOS FET	Break Down Voltage	VL	400	V	
	Continuous Load Current	lι	150	mA/ch	
	Pulse Load Current <sup>2</sup> (AC/DC Connection)	ILP	300	mA/ch	
	Power Dissipation	Po	375	mW/ch	
Isolation Voltage *3		BV	1 500	Vr.m.s.	
Total Power Dissipation		Рт	850	mW	
Operating Ambient Temperature		TA	-40 to +85	°C	
Storage Temperature		T <sub>stg</sub>	-40 to +100	°C	

<sup>\*1</sup> PW = 100  $\mu$ s, Duty Cycle = 1%

## RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	TYP. MAX.	
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

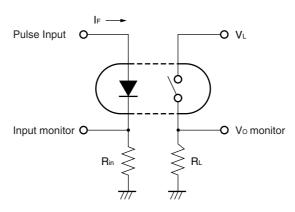
<sup>\*2</sup> PW = 100 ms, 1 shot

<sup>\*3</sup> AC voltage for 1 minute at  $T_A = 25^{\circ}C$ , RH = 60% between input and output Pins 1-4 shorted together, 5-8 shorted together.

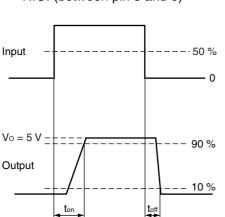
## **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	٧
	Reverse Current	lR	V <sub>R</sub> = 5 V			5.0	μΑ
MOS FET	Off-state Leakage Current	Loff	N.O.: IF = 0 mA, VD = 400 V		0.03	1.0	μΑ
			N.C.: I <sub>F</sub> = 10 mA, V <sub>D</sub> = 400 V				
	Output Capacitance	Cout	N.O.: V <sub>D</sub> = 0 V, f = 1 MHz		65		pF/ch
			N.C.: V <sub>D</sub> = 0 V, f = 1 MHz, I <sub>F</sub> = 10 mA		185		
Coupled	LED On-state Current	<b>I</b> Fon	N.O.: I∟ = 150 mA			2.0	mA
	LED Off-state Current	<b>I</b> Foff	N.C.: IL = 150 mA			2.0	mA
	On-state Resistance	R <sub>on1</sub>	N.O.: I <sub>F</sub> = 10 mA, I <sub>L</sub> = 10 mA		20	30	Ω
			N.C.: IF = 0 mA, IL = 10 mA		24	30	
		Ron2	N.O.: IF = 10 mA, IL = 150 mA, $t \le 10$ ms		16	25	
			N.C.: $I_F = 0 \text{ mA}, I_L = 150 \text{ mA}, t \le 10 \text{ ms}$		16	25	
	Turn-on Time*1,2	ton (N.O.)	IF = 10 mA, Vo = 5 V, RL = 500 $\Omega$ ,		0.33	1.0	ms
		ton (N.C.)	PW ≥ 10 ms		0.02	0.2	
	Turn-off Time*1,2	toff (N.O.)			0.03	0.2	
		toff (N.C.)			0.20	1.0	
	Isolation Resistance	Ri-o	Vi-o = 1.0 kVpc	10°			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		1.1		pF/ch

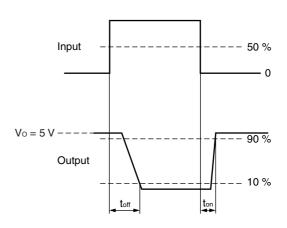
### \*1 Test Circuit for Switching Time



N.O. (between pin 5 and 6)

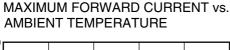


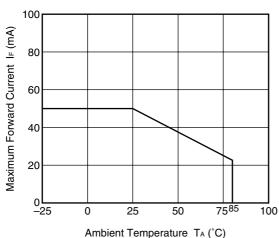
N.C. (between pin 7 and 8)



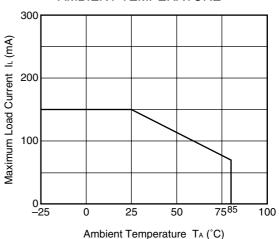
<R> \*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

#### TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

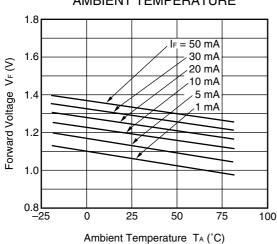




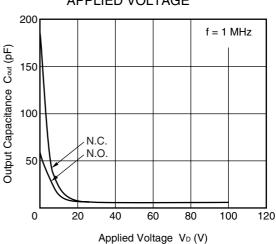
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



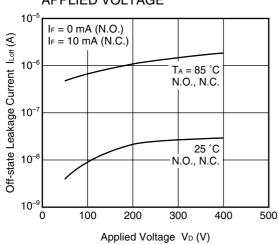
FORWARD VOLTAGE vs. AMBIENT TEMPERATURE



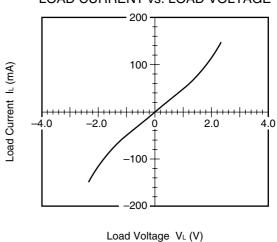
OUTPUT CAPACITANCE vs. APPLIED VOLTAGE



OFF-STATE LEAKAGE CURRENT vs. APPLIED VOLTAGE

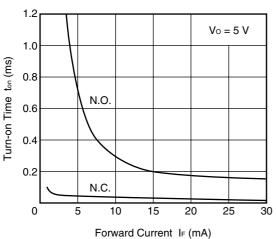


LOAD CURRENT vs. LOAD VOLTAGE

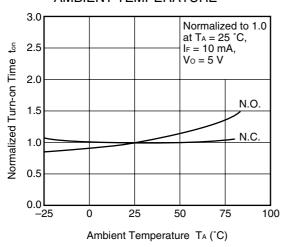


**Remark** The graphs indicate nominal characteristics.

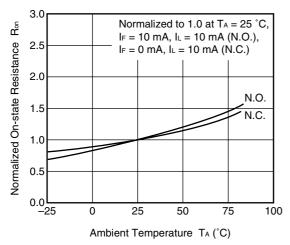
#### TURN-ON TIME vs. FORWARD CURRENT



## NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

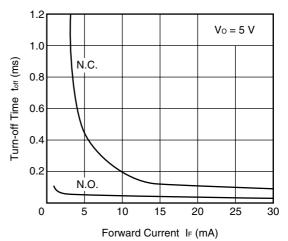


## NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE

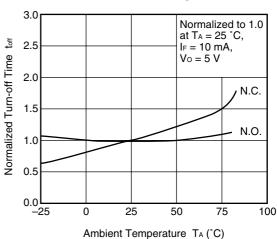


**Remark** The graphs indicate nominal characteristics.

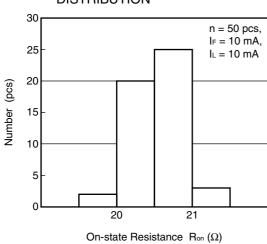
#### TURN-OFF TIME vs. FORWARD CURRENT



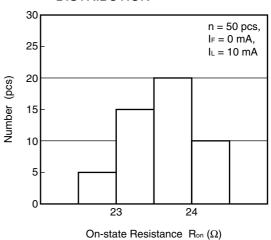
## NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



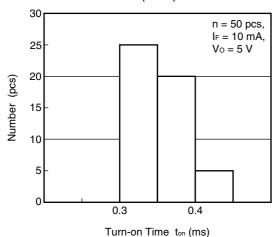
## ON-STATE RESISTANCE (N.O.) DISTRIBUTION



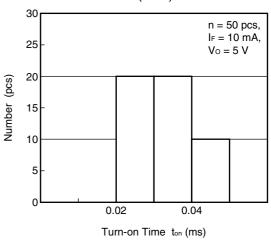
## ON-STATE RESISTANCE (N.C.) DISTRIBUTION



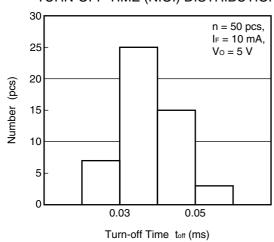
## TURN-ON TIME (N.O.) DISTRIBUTION



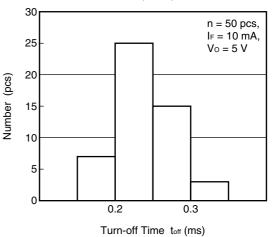
## TURN-ON TIME (N.C.) DISTRIBUTION



## TURN-OFF TIME (N.O.) DISTRIBUTION

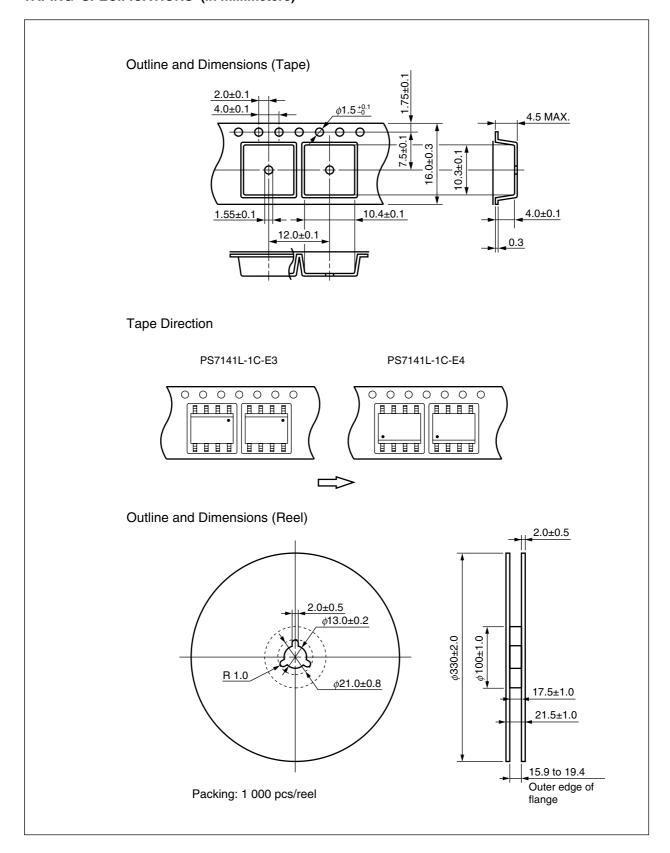


TURN-OFF TIME (N.C.) DISTRIBUTION



**Remark** The graphs indicate nominal characteristics.

## **TAPING SPECIFICATIONS (in millimeters)**



#### RECOMMENDED SOLDERING CONDITIONS

#### (1) Infrared reflow soldering

• Peak reflow temperature 260°C or below (package surface temperature)

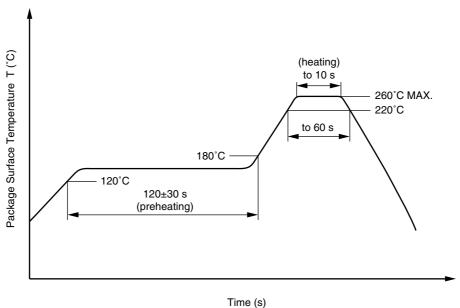
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

### Recommended Temperature Profile of Infrared Reflow



#### Tille (s

#### (2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

• Preheating conditions 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

## <R> (3) Soldering by soldering iron

Peak temperature (lead part temperature) 350°C or below
 Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

#### (4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

## <R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

#### Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
  - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

#### ▶ For further information, please contact

### **NEC Compound Semiconductor Devices Hong Kong Limited**

E-mail: contact@ncsd-hk.necel.com

Hong Kong Head Office TEL: +852-3107-7303 FAX: +852-3107-7309
Taipei Branch Office TEL: +886-2-8712-0478 FAX: +886-2-2545-3859
Korea Branch Office TEL: +82-2-558-2120 FAX: +82-2-558-5209

#### NEC Electronics (Europe) GmbH http://www.eu.necel.com/

TEL: +49-211-6503-0 FAX: +49-211-6503-1327

California Eastern Laboratories, Inc. http://www.cel.com/

TEL: +1-408-988-3500 FAX: +1-408-988-0279

Compound Semiconductor Devices Division NEC Electronics Corporation URL: http://www.ncsd.necel.com/